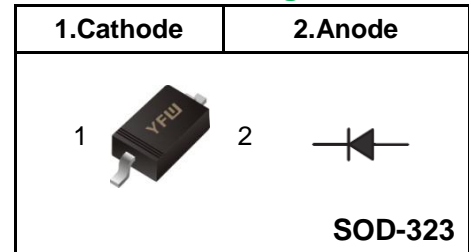


FEATURES

- ◆ For surface mounted applications
- ◆ Glass Passivated Chip Junction
- ◆ Fast reverse recovery time
- ◆ Ideal for automated placement
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives



Pinning



MECHANICAL DATA

- ◆ Case: SOD-323
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 4.5mg /0.00016oz

Marking Code

BAV19WS	A8
BAV20WS	T2
BAV21WS	T3

Absolute Maximum Ratings at 25 °C

Parameter	Symbols	BAV19WS	BAV20WS	BAV21WS	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	120	200	250	V
Maximum RMS voltage	V_{RMS}	100	150	200	V
Continuous Forward Current	I_F	250			mA
Repetitive Peak Forward Current	I_{FRM}	625			mA
Non-reptitive Peak Forward Surge Current	I_{FSM}	at 1s			A
		at 1ms			
		at 1us			
Total Power Dissipation	P_{tot}	500			mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150			°C

Characteristics at Ta = 25 °C

Parameter	Symbols	BAV19WS	BAV20WS	BAV21WS	Units
Reverse Breakdown Voltage at $I_R=100\mu A$	$V_{(BR)R}$	120	200	250	V
Maximum Forward Voltage	V_F	at 100 mA			V
		at 200 mA			
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ C$			uA
		$T_a=150^\circ C$			
Typical Junction Capacitance at $V_R=4V, f=1MHz$	C_j	5			pF
Maximum Reverse Recovery Time	T_{rr}	50			nS

Fig.1 Power Derating Curve

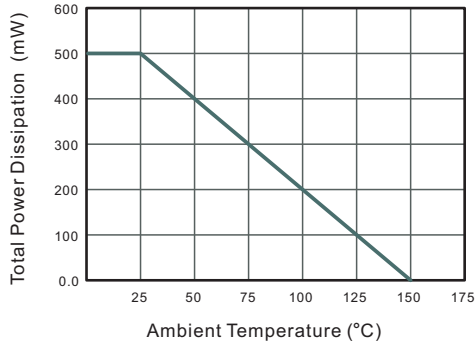


Fig.2 Typical Reverse Characteristics

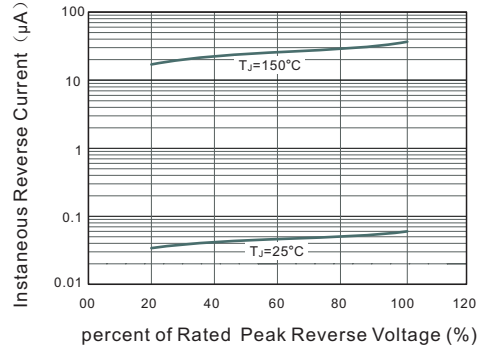


Fig.3 Typical Instantaneous Forward Characteristics

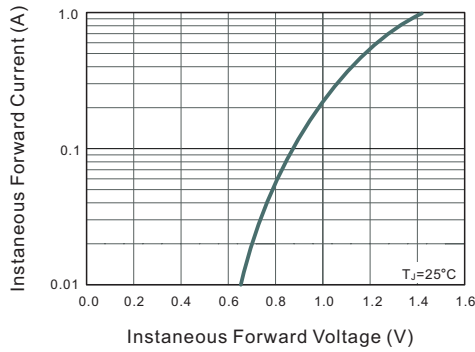
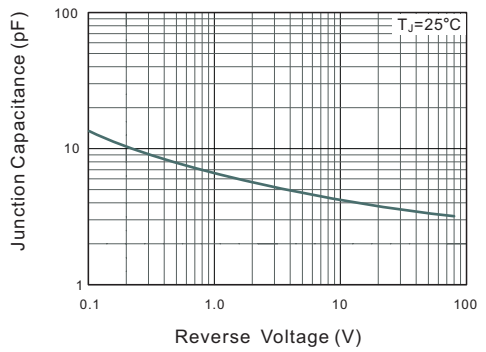
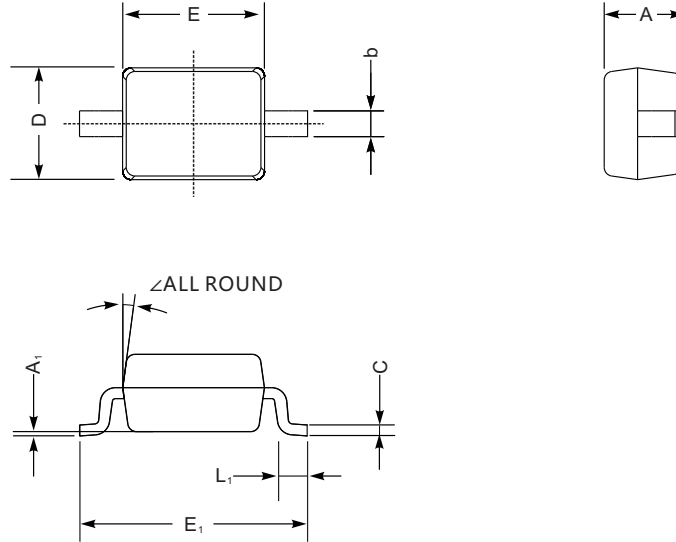


Fig.4 Typical Junction Capacitance



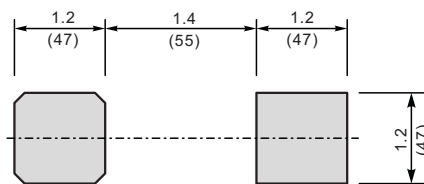
Package Outline SOD-323

Plastic surface mounted package; 2 leads



UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	\angle
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	

The recommended mounting pad size



Unit: $\frac{\text{mm}}{\text{mil}}$

Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SOD-323	Tape/Reel, 7" reel	3000	EIA-481-1